

YF Series

Indoor Fixed COB Panel



FCOB

Flip-Chip on Board

LED Chip

PCB

Specifications

Model	YF0.9	YF1.2
Pixel Pitch Exhibited(mm)	0.93	1.25
LED Type	COB (Flip chip)	COB (Flip chip)
Module Size(WxH)	300×337.5	300×337.5
Pixel Per Module(dots)	320×360	240×270
Panel Size(mm)	600×337.5×40 / 600×675×40	600×337.5×40 / 600×675×40
Pixel Per Panel(dots)	640×360 / 640×720	480×270 / 480×540
Material	Die casting aluminum	Die casting aluminum
Weight(kg/panel)	5.6 / 9.8	5.4 / 9.8
Brightness(nits)	1200	2400
Gray scale (bit)	13	13
Refresh rate (Hz)	4320	4200
Color Temperature(K)	3200~9300	3200~9300
Viewing angle(H)	170°	170°
Viewing angle(V)	160°	160°
Power Max. (W/m ²)	350	560
Operating Temperature(°C)	-10~+45	-10~+45
Module IP Rating (Front)	IP65	IP65
Installation/Maintenance	Front	Front

Remark: Power consumption tolerance: ±15%, according to the actual situation.
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Integrated Cabinet

The integrated cabinet results in good tightness and high overall protection



Energy Saving

Reduce the loss and save the resources



Module Blackening Processing

Significantly improves black color consistency and enhances contrast



High Brightness

The maximum brightness can reach 2400 nits to meet the requirements of different application scenarios



Soft Eye Protection

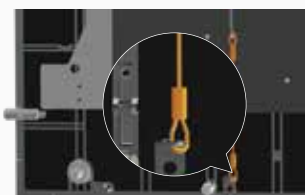
Surface light source design, uniform light output, German Rheinland TUV low blue light certification, softer and more eye-protectin



Aluminum Bottom Shell



Module with aluminum bottom shell for superior cooling and radiation protection



Equipped with a safety rope for ensured security



Higher strength and splicing accuracy.